PR No. 1000007467 SRM/RFx 6100000121 DSB (Double Sided PCB) Fabrication Process Flow

Highlighted processes will be handled separately **Shearing Machine** - Cut Copper Clad Laminate (CCL) to Size NC Drill Data **CNC** Drilling Machine - Drill CCL as per drill drawing from design **Brushing Machine** Debur drilled holes **Electroless Plating Machine** Clean & Prepare the drilled holes for Electro Plating **Electro-Plating Machine** - Electroplate the drilled holes with Copper **Brushing Machine** Brush the platted CCL for removing any blemishes Dry Film Laminator Laminate the CCL with Dry Film Resist (DFR) Film Master for **UV Exposure Machine** Top and Bottom Expose the CCL for the required Copper pattern **Developing Machine** Develop the etch resist for required pattern **Electroplating Machine** Electroplate the pattern and holes withTin Stripping of DFR Remove unwanted dry film resist from CCL

